

## PCN20025: Migration of Solder Paste for Package Decoupling Capacitors from RoHS to Sn/Pb for PolarFire Military Temperature Devices

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December 15, 2020

### Description

The solder paste used for package decoupling capacitors will migrate from a RoHS-compliant solder paste to an Sn/Pb (63/37) solder paste.

### Reason for Change

To mitigate against tin whisker growth.

### Application Impact

None.

### Method of Identifying Changed Product

By part number.

### Products Affected

MPF300TS-FC484M	MPF500TS-FC784M	MPF500TS-FC1152M
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### Product Shipment Schedule

12 weeks ARO

### Qualification Data

No new qualification is needed for the following reasons:

- SnPb was the standard solder paste before RoHS for packaging and PCB surface mount interconnect and there are many years field service history, and there is not reliability issue.
- In RT4G150 devices, we are using Sn/Pb solder paste for attaching de-caps, and devices passed all MIL-PRF-38535.
- However, we will amend PA-224 (Qualify PolarFire MPF500T-FCG1152 and smaller packages) with BOM included Sn/Pb solder paste for de-caps attachment.
- Additionally, package solder balls are using Sn/Pb for attachment already in the existing PA-224 qualification.

### Samples Availability

12 weeks

### Contact Information

If you have any questions about this subject, contact Microsemi Technical Support department by using the support portal at <https://soc.microsemi.com/Portal/Default.aspx>

### Regards,

Microsemi Corporation

Any projected dates in this notification are based on the most current product information at the time this notification is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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